## TI TECH DAYS

### Buck Switching Regulator Power Modules Get to market faster with reduced EMI and smaller power supply size

Stephen Ott – Product Marketing Engineer, Denislav Petkov – Applications Manager

**Speaker organization** 



### **Presenters**



#### **Stephen Ott**

Marketing Engineer Wide VIN Power



#### Alejandro Iraheta

Applications Engineer Wide VIN Power

### Short bio:

Stephen Ott is a product marketing engineer for the Wide Vin team at Texas Instruments. Stephen started his career at National Semiconductor in 2005 in power management. Throughout his career he has held various marketing roles related to power at National Semiconductor and Texas Instruments.

Stephen is based in Santa Clara, California.

### Short bio:

Alejandro Iraheta is an applications engineer for the Wide Vin Converter and Modules team at Texas Instruments. He started his career with TI in 2018 and has been involved with power electronics since.

Alejandro is based in Warrenville, Illinois.

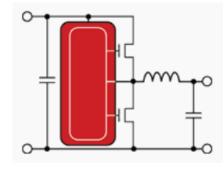


## **Topics**

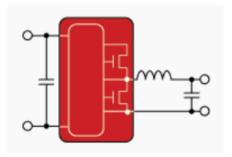
- Speed up the power supply design cycle & save board space
- EMI sources and mitigation
- Inductor selection and design tradeoffs
- New module packaging technology & product highlights
- Design tools & support



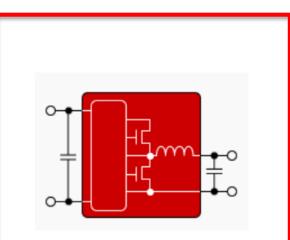
## Step-down (buck) switching regulators



- External FETs
- External inductor



- Internal FETs
- External inductor



- Internal FETs
- Internal inductor
- Internal caps and resistors



# Speed up the power supply design cycle & save board space



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### How modules shorten the design cycle

- Module designer does the heavy lifting
  - Optimal converter selected to cover design specifications
  - Selects BOM components optimal for converter
  - Characterizes solution across corner cases
  - Leverages latest technology to meet market requirements
  - Rigorous vetting of internal BOM components not every inductor or capacitor is created equal
- Inherent module benefits reduce or eliminate
  - Control architecture influences
  - Layout challenges
  - Inductor sourcing
  - Lab prototyping



### **Quick design example with TPSM53604**

#### Step 1. Select resistors to set the output voltage

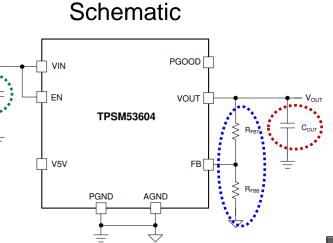
Table 1. Setting the Output Voltage					
V <sub>OUT</sub> (V)	R <sub>FBB</sub> (kΩ) <sup>(1)</sup>	C <sub>OUT(MIN)</sub> (µF) (EFFECTIVE)	V <sub>OUT</sub> (V)	R <sub>FBB</sub> (kΩ) <sup>(1)</sup>	C <sub>OUT(MIN)</sub> (µF) (EFFECTIVE)
1.0	open	150	3.0	4.99	57
1.1	100	143	3.3	4.32	52
1.2	49.9	132	4.0	3.32	43
1.3	33.2	123	4.5	2.87	39
1.4	24.9	115	5.0	2.49	35
1.5	20.0	107	5.5	2.21	32
1.8	12.4	91	6.0	2.00	30
2.0	10.0	82	6.5	1.82	28
2.5	6.65	67	7.0	1.65	26

### Step 2. Select input capacitor

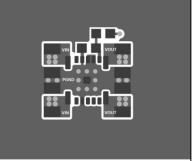
Table 2. Recommended Input Capacitors <sup>(1)</sup>							
		SIZE	PART NUMBER	CAPACITOR CHA	CAPACITOR CHARACTERISTICS		
VENDOR	SERIES			VOLTAGE RATING (V)	CAPACITANCE (2) (µF)		
Murata	X5R	1206	GRT31CR61H106ME01L	50	10		
TDK	X5R	1206	CGA5L3X5R1H106M160AB	50	10		
TDK	X7R	1206	CGA5L1X7R1H106K160AC	50	10		
Murata	X7R	1210	GRM32ER71H106KA12L	50	10		
TDK	X7R	1210	C3225X7R1H106M250AC	50	10		

#### Step 3. Select output capacitor

Table 3. Recommended Output Capacitors <sup>(1)</sup>						
		PART NUMBER	CAPA	CAPACITOR CHARACTERISTICS		
VENDOR	SERIES		VOLTAGE RATING (V)	CAPACITANCE (2) (µF)	ESR <sup>(3)</sup> (mΩ)	
TDK	X5R	C3225X5R0J476K	6.3	47	2	
Murata	X7R	GCM32ER70J476KE19L	6.3	47	2	
Murata	XSR	GRM21BR61A476ME15L	10	47	2	
TDK	X5R	C3216X5R1A476M160AB	10	47	2	
Murata	X7R	GRM32ER71A476KE15L	10	47	2	
Murata	X5R	GRM32ER61C476K	16	47	3	
TDK	X5R	C3225X5R0J107M	6.3	100	2	
Murata	X5R	GRM32ER60J107M	6.3	100	2	
Murata	X5R	GRM32ER61A107M	10	100	2	
Kemet	X5R	C1210C107M4PAC7800	16	100	2	
Panasonic	POSCAP	6TPE100MI	6.3	100	18	
Panasonic	POSCAP	10TPF150ML	10	150	15	
Panasonic	POSCAP	6TPF220M9L	6.3	220	9	
Panasonic	POSCAP	6TPF330M9L	6.3	330	9	
Panasonic	POSCAP	6TPE470MAZU	6.3	470	35	



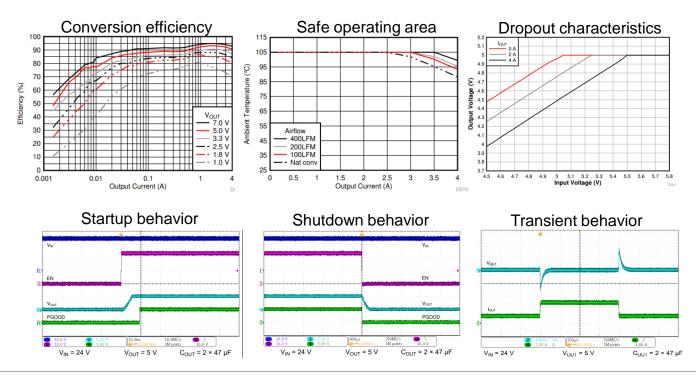
See layout example for the PCB design





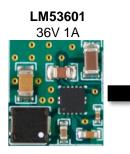
## Power supply performance already characterized

• The inductor is already part of the package - the datasheet curves represent the actual solution



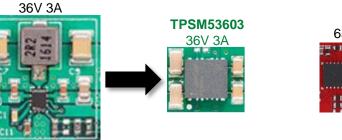


## **Board area savings through integration**





LMR33630



LM5165 65V 150mA

**TPSM265R1** 65V 100mA

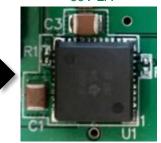




LM46002 60V 2A



LMZ36002 60V 2A





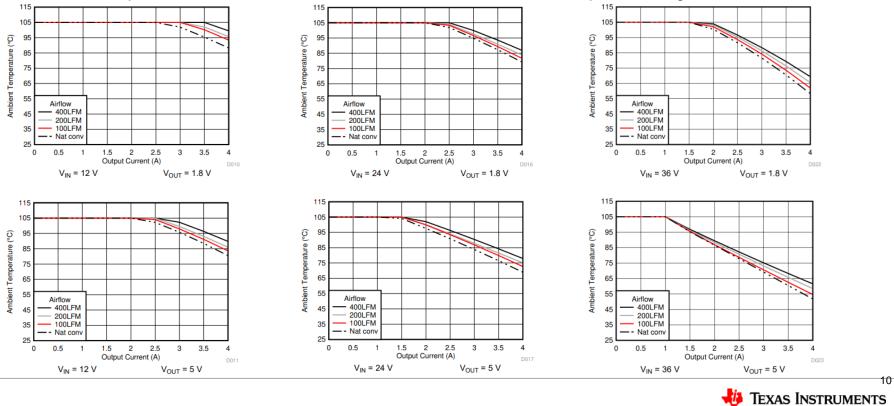
LMR23630

LMZM33603 36V 2A



### Help with thermal design

SOA curves provided in the datasheet across the VIN, VOUT, IOUT, and Temperature range

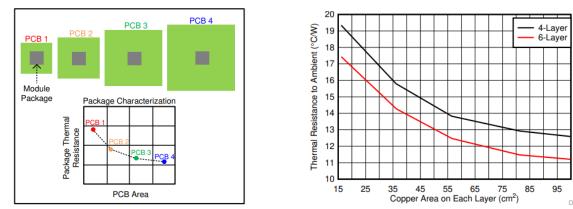


## Help with thermal design

• Package thermal performance characterized across different board areas for easier thermal design



Contents	
Introduction	2
Power Modules and Thermal Design	2
Thermal Design Steps	2
Design Example with LMZM33606	4
Thermal Characteristics of Various DC/DC Module Packages	5
Conclusion	7
References	8



- 1. Look up the power dissipation.
- 2. Calculate required thermal resistance.
- 3. Estimate necessary board area from plot.

Figure 1. Package Characterization and Thermal Resistance Plot Versus Board Area

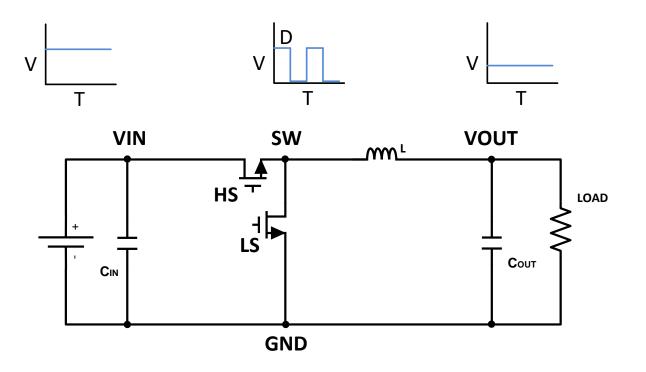
Figure 4. LMZM33606 16.00 mm × 10.00 mm QFN Package



## **EMI sources and mitigation**

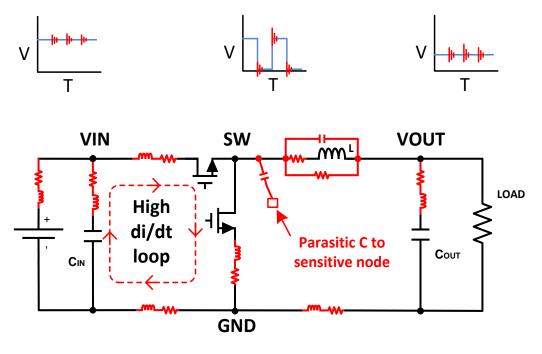


### The buck regulator





### Less ideal buck regulator

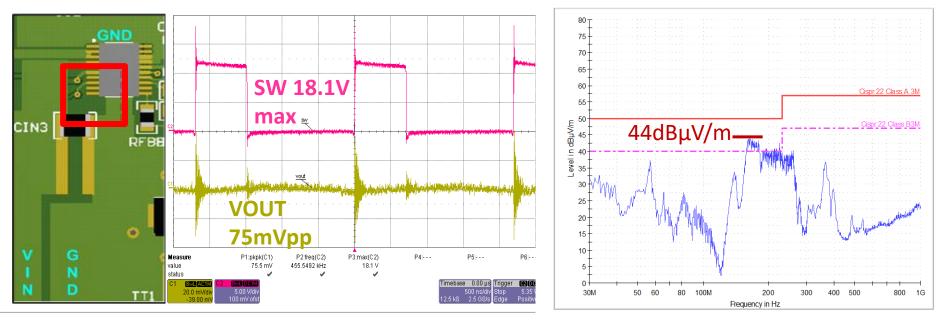


"Free" components in red



## High di/dt capacitor placement - example

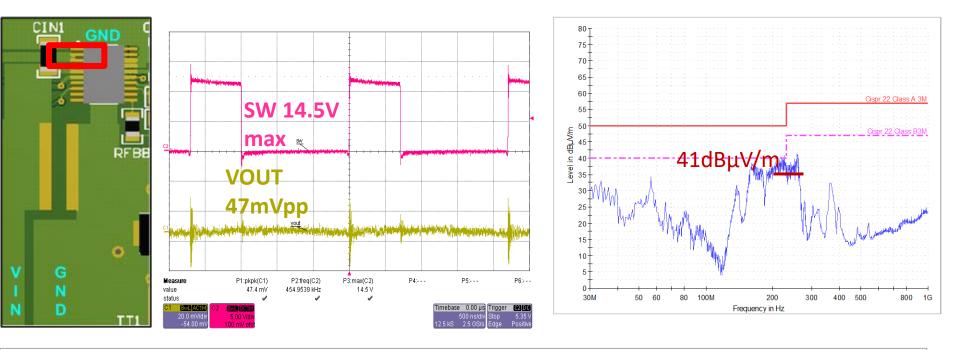
- Buck Regulator comparison with Cin location
- 12V input, 3.3V output, 2A Buck





## High di/dt capacitor placement - example

- Buck Regulator comparison with Cin location (2 times smaller loop area)
- 12V input, 3.3V output, 2A Buck





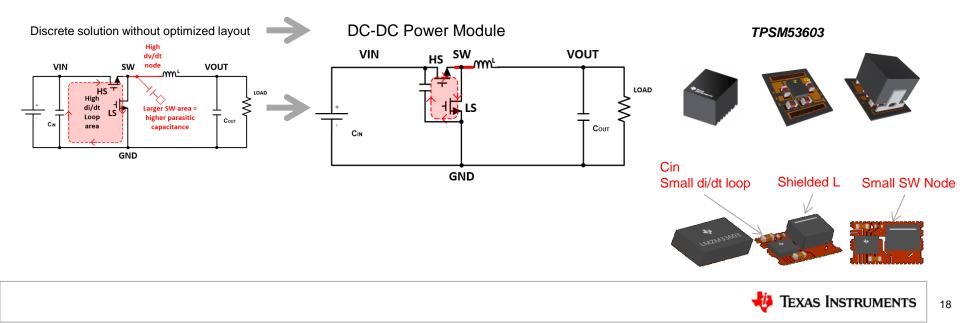
## Noise reduction and component placement

- For a Buck converter...
  - The INPUT cap position affects the OUTPUT noise!
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### **EMI advantages by optimizing layout**

- Reducing the high di/dt loop area integrated input capacitance.
- Reducing the high dv/dt node area integrated L and smaller switch node.

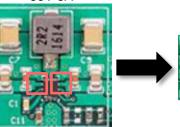


## Input loop area estimate for converter and module





36V 3A





LMR23630

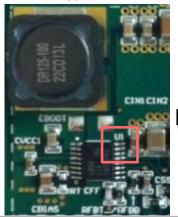
LM5165 65V 150mA

**TPSM265R1** 65V 100mA

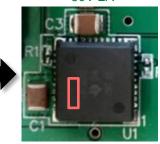


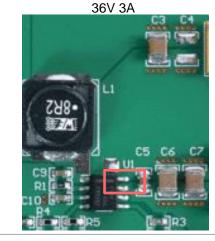


LM46002 60V 2A



LMZ36002 60V 2A

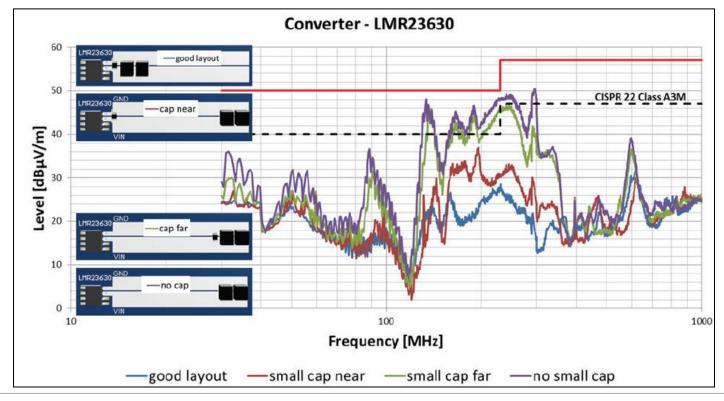






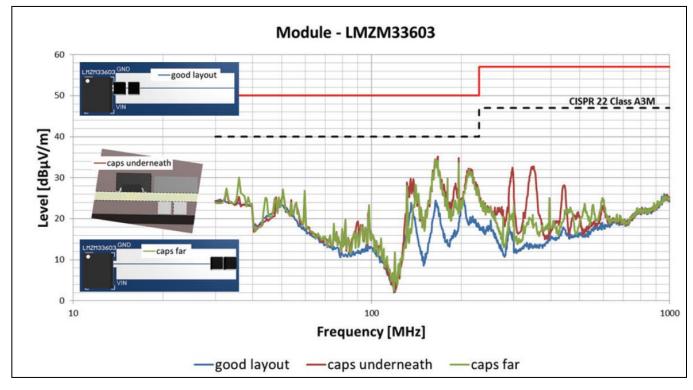


# LMR23630 EMI comparison with different cap positions



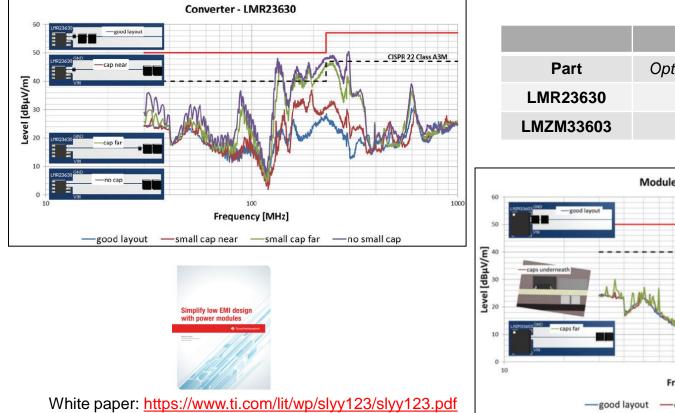


## LMZM33603 EMI comparison with different cap positions

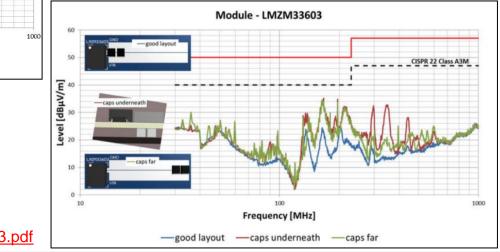




### LMR23630 vs LMZM33603 EMI summary

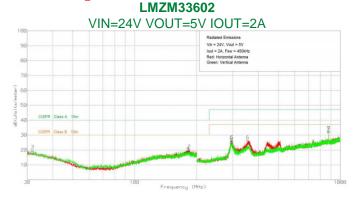


	Peak dBuV/m		
Part	Optimal Layout	Poor Layout	
LMR23630	29	46	
LMZM33603	25	35	





### **EMI performance of modules – CISPR11 Class B**

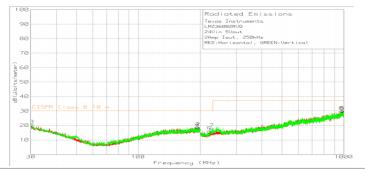


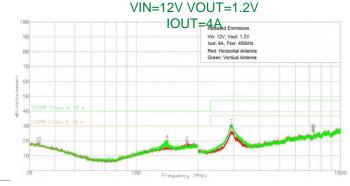
CISER Class # 10 # 1000 Figure Class # 1000 Figure Class

**TPSM53602** 

Figure 47. Radiated Emissions 12-V Input, 5-V Output, 2-A Load

#### LMZ36002 VIN=24V VOUT=5V IOUT=2A







### Inductor selection and design tradeoffs



### **Inductor selection**

- Inductor selection is one of the most important aspects of the DC-DC converter design
  - Inductor characteristics
    - Inductance value
      - Affects size, ripple, transient response, peak current, efficiency
    - Winding resistance
      - Affects size, ripple, dropout, efficiency
    - Core material
      - Affects size, core power losses
    - Saturation current
      - Affects size, peak current, overload protection
    - Shielding
      - Affects EMI performance



### **Component selection for modules**

- Passive components undergo additional screening for modules
  - Strict requirements for internal BOM selection
    - Industrial grade & approved TI vendor
  - Additional screening beyond passive manufacturer testing
    - Lifetime testing
    - High temperature storage
    - Capacitance vs. DC bias
    - Insulation resistance
    - 3x Reflow, monitor change in C and IR
    - Inductance vs. DC current vs. Temperature (saturation)



## **Design tradeoffs for modules**

- Single inductance value puts constraints on several parameters of the power module
  - Minimum and maximum switching frequency
  - Output voltage range
  - Efficiency

### **Examples:**

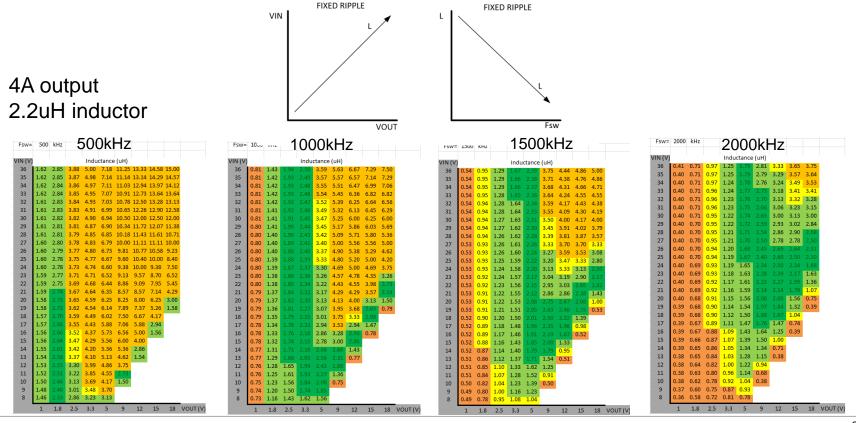
TPSM53604 Module output range: 1V to 7V LMR33630 IC output range: 1V to 24V

LMZ36002 Module output range: 2.5V to 7.5V LM46002 IC output range: 1V to 24V

Modules are usually optimized to cover the most common output rails with good performance.

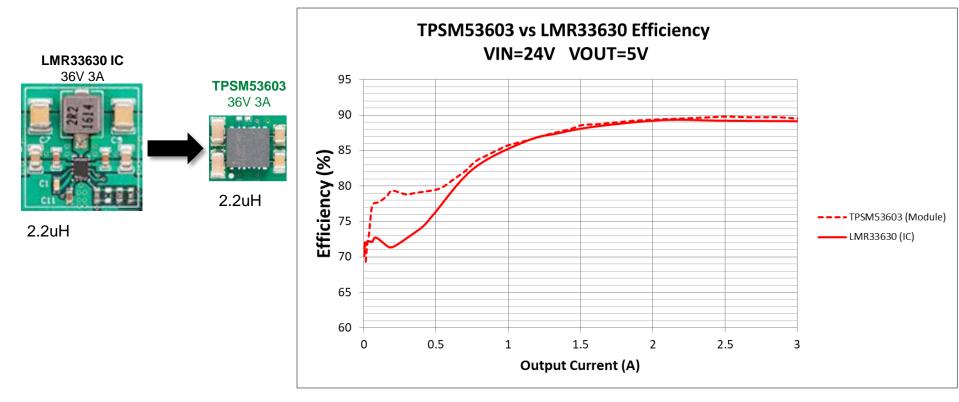


### **Inductance requirements**



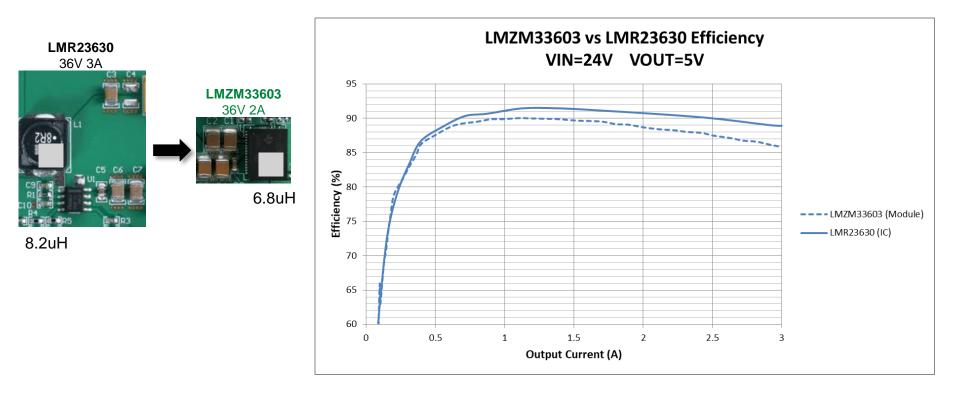


### **Performance comparison**



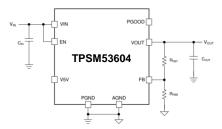


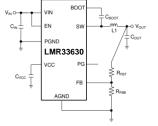
## **Performance comparison**

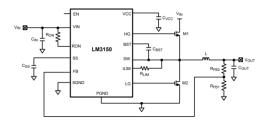




### Like everything in life – it's a tradeoff







	Power Module	Converter	Controller
Breadth of portfolio	Emerging – fewer options to consider (pro/con)	Mature – many options can be great but also overwhelming	Mature – many options
Design difficulty (component selection & layout)	Easy	Moderate	Difficult
Solution Size	Smallest	Small-Medium but depends on IC and passive selection	Large
EMI	Low without effort	Low-Medium (depends on component selection & layout)	Depends on layout
Design Flexibility	Less – FETs and inductor fixed	Moderate – FETs fixed	High – select FETs & inductor
Total BOM Cost (\$\$\$ to \$)	\$\$\$ to \$\$	\$\$ to \$	\$\$ to \$



## Which is the best fit for your application?

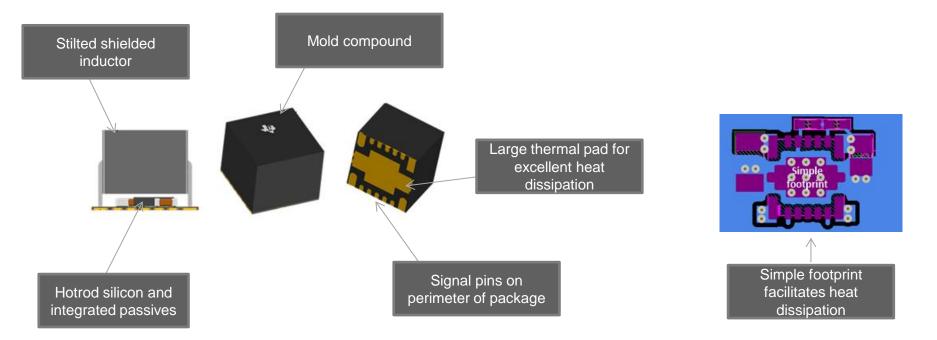
- Consider a module
  - Limited time and resources
  - Limited board space
  - Save on total cost (engineering and material cost)
- Consider a converter or controller
  - BOM cost is #1 priority
  - Specific requirements outside of module operating range



# New module packaging technology & product highlights

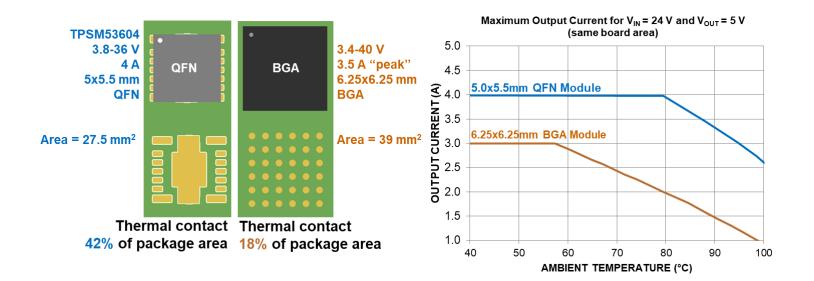


### Introduction to Enhanced HotRod<sup>™</sup> QFN package





## Enhanced HotRod QFN packaging thermal performance compared to competition





### **TPSM53604/3/2**

### Industry's highest density 36V, 2A/3A/4A power module

### **Features**

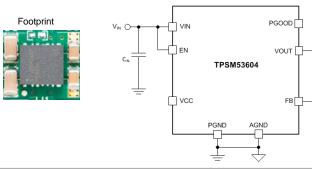
- Enhanced HotRod<sup>™</sup> QFN Packaging
- 4 to 36V Input Voltage Range
- 2A, 3A, and 4A Output Current Options
- 1V to 7V Output Voltage Range
- 5 x 5.5 x 4mm QFN Package
- -40 °C 105 °C Operating Temp Range (125 °C Junction)
- Pin out engineered to reduce EMI
- High efficiency across load range
- PG, Pre-Biased Start Up and Prog UVLO
- LMR33630 Silicon

### Applications

- Factory Automation
- Test & Measurement
- Grid
- Defense
- Industrial Transport

### Benefits

- Reduced design risk integrated inductor and small passives in easy to handle QFN packaging
- Smallest 36V, 4A/3A solution (30% smaller than discrete implementation and competition module solution)
- Best in class efficiency (89% at 24Vin, 5Vout, 3A)
- Up to 20W output power at 85°C with no airflow
- Low EMI Meets CISPR11 radiated emissions





R<sub>FBT</sub>

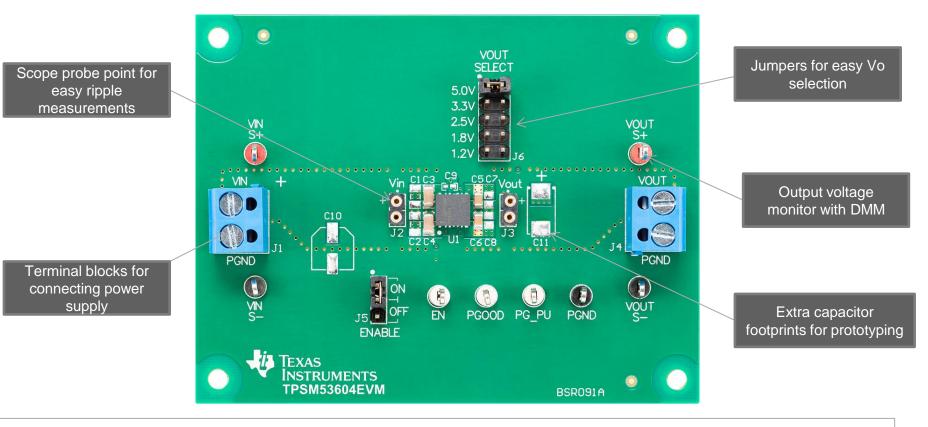
R<sub>FBB</sub>

O Vout

-C<sub>OUT</sub>

**Newly Released!!** 

# **Evaluating the TPSM53604**





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# Introduction to system-in-package

System-in-Package integrates the IC inside a laminate substrate with SMD components on top of the package

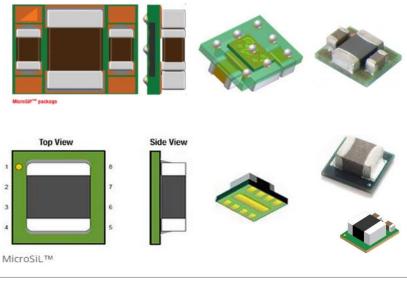
Texas Instruments is the first company that made high volume production with this packaging technology as MicroSiP<sup>™</sup> and MicroSiL<sup>™</sup> with an embedded die Picostar<sup>™</sup>

#### MicroSiP

- Fully embedded IC inside substrate
- <u>ALL</u> Passive components (L, C<sub>IN</sub>, C<sub>OUT</sub>) are on top
- Module package is BGA (WCSP) format

#### MicroSiL

- Same packaging technology as MicroSiP<sup>™</sup>
- Passive components are on top
- Module package is in QFN format





# LMZM23600/1



#### Industry's smallest 36V Input 0.5A/1A step-down DC/DC Module

#### **Features**

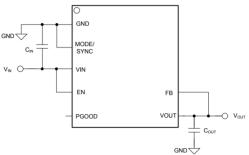
- 4 to 36V Input Voltage Range, Transient to 42V
- 0.5A and 1A Output Current Options
- Fixed 3.3V, 5V & Adj (2.5V 15V) Output Voltage Range
- Miniature 3 x 3.8 x 1.6mm Package (0.6mm Pitch)
- Low EMI: Tested to CISPR11 Class B Radiated EMI
- Mode Pin
  - Forced PWM Mode w/ Freq Sync
  - Auto PFM Mode option for Light Load Efficiency
- -40 °C to 125 °C Operating Junction Temperature
- Built in Compensation, Soft Start, Current Limit, Thermal Shutdown, Power Good, and Input UVLO

### **Applications**

- Factory & Building Automation
- Medical Equipment
- Smart Grid & Energy
- Defense Equipment
- Inverting Output Application Note

- · Supports wide range of application requirements
- Easy to Design: only C<sub>IN</sub> and C<sub>OUT</sub> required (Fixed Vout)
  27mm<sup>2</sup> solution: 45% smaller than competition; 55% smaller
- 27mm<sup>2</sup> solution: 45% smaller than competition; 55% smaller than discrete
- System Flexibility with choice of Fixed Frequency or Light Load Efficiency
- Synchronize to external clock







# TPS82130 / TPS82140 / TPS82150

#### 17V 1-A to 3-A step down converter module with integrated inductor

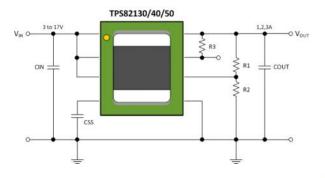
#### Features

- MicroSiP<sup>™</sup> package with integrated inductor 3.0mm x 2.8mm x 1.5mm
- 3V to 17V Input Voltage Range
- DCS-Control<sup>™</sup> Topology
- Power Save Mode for Light Load Efficiency
- 100% Duty Cycle
- 20µA Quiescent Current
- Power Good Output plus Capacitor Discharge
- Adjustable Output Voltage
- Programmable Soft Startup
- -40°C to 125°C operating temperature range

## Applications

- General Purpose POL
- Data cards, Network Switcher, Line Cards
- Storage: Server, Motherboards
- Telecom Infrastructure: Optical Modules (Inverter)

- Small, low profile solution
- Saves >50% PCB area (TPS82130), compared to discrete solution
- Easy to use



Device Name	Output Current	
TPS82130SIL	3-A	la l
TPS82140SIL	2-A	14500
TPS82150SIL	1-A	





# **TPSM82821/2**

### 1A/2A buck converter with integrated inductor

#### **Features**

- 2.0 x 2.5 x 1.1mm SIL package with integrated inductor
- $V_{IN} = 2.4V$  to 5.5V /  $V_{OUT} = 0.6V$  to 4.0V (adjustable)
- 4µA Quiescent Current
- Up to 95% Efficiency
- DCS-Control<sup>™</sup> Topology
- Power Save Mode for Light Load Efficiency
- V<sub>REF</sub>= 0.6V with 1% accuracy
- Hiccup Short Circuit Protection
- Active Output Discharge, Power Good Output
- Integrated Soft start

## **Applications**

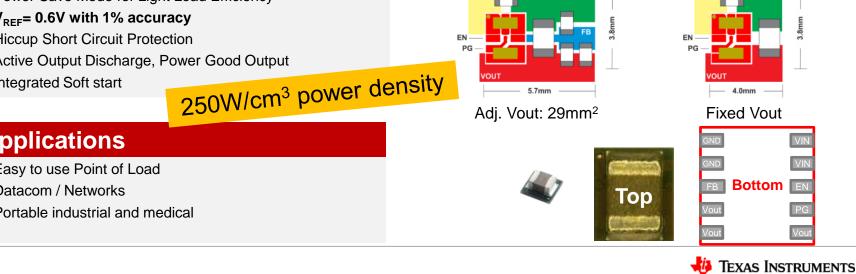
- · Easy to use Point of Load
- Datacom / Networks
- Portable industrial and medical

#### **Benefits**

Small, low profile solution for small form factor applications

Preview Samples available at TI.com

- Easy to use, proven solution
- DCS-Control Topology maintains an accurate output voltage at fast line and load transients plus a seamless transition between PWM and power save mode



# **TPSM82813/0**

#### 3A/4A buck converter with integrated inductor

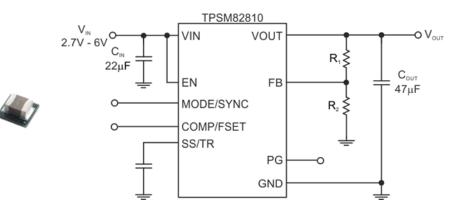
#### Features

- 2.5V to 6V input voltage range
- Adjustable output voltage from 0.6V to Vin
- -40°C to 150°C operating junction temperature range
- 1% output voltage accuracy
- 10uA Quiescent current
- Fixed frequency operation, per default at 2.2MHz
- Adjustable switching frequency and compensation
- Forced PWM and external synchronization (1.8 4MHz)
- SS/TR provides adjustable soft-start and tracking capability
- Output discharge for defined ramp-down of Vout
- Spread Spectrum Clocking for decreased noise (optional)
- Package 3x4x2.5mm embedded uSIL

## Applications

- Factory Automation
- Test & Measurement
- Medical
- Communications Equipment

- Small solution size with minimal external components
- Fixed frequency, external sync and Spread Spectrum Clocking facilitates design for low EMI
- Short min on-time of 50ns allows direct conversion of 5V to 1V at f>2MHz
- Allows wide range of output capacitance to meet requirements for input of FPGAs or MCUs





# **TPSM265R1**

#### Industry's highest density 65V, 100mA power module with ultra low Iq

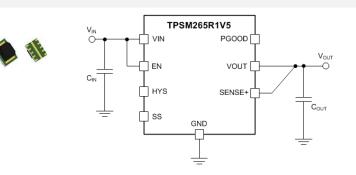
#### **Features**

- Input voltage range from 3V to 65V
- 10.5 $\mu$ A no-load I<sub>Q</sub>, 2  $\mu$ A Shutdown I<sub>Q</sub>
- PFM Mode For Excellent Light Load Efficiency
- Miniature 2.8mm x 3.7mm x 1.9mm package with integrated inductor
- Output Voltage options:
  - 3.3V, 5V Fixed Vout
  - 1.3V to 15V Adjustable Output Voltage
- Power Good flag, Internal + external soft start
- Precision input UVLO

### **Applications**

- Factory Automation
- Process and Field Sensors
- 4-20 mA current-loop powered sensors

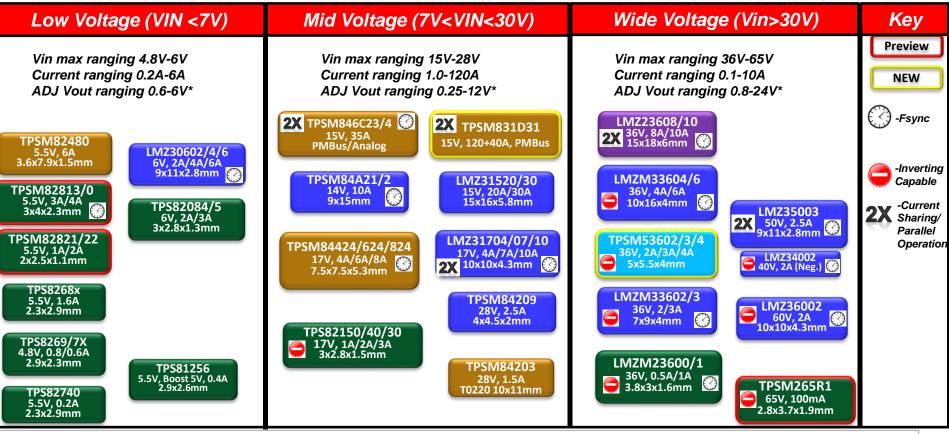
- Continuous 65V operation. No need to transient suppressors.
- Smallest 65V capable 100mA solution
- Fixed output voltage versions guarantee lowest BOM count (Just
  C<sub>IN</sub> and C<sub>OUT</sub> required)
- Form Factor and pin out engineered to:
  - Ensure one side to be no more than 3mm
  - Ensure small switching current loops and low noise operation





## **Power module hero portfolio**





\*Vout range is portfolio wide not device specific



# **Design tools & support**



## **TI.com resources**

## **EMI** reduction and noise mitigation:

- App Note: Simple Success With Conducted EMI From DCDC Converters
- App Note: Simplify low EMI design with power modules
- <u>App Note: PCB layout techniques for low noise power designs</u>
- Tech Article: Design a second-stage filter for noise sensitive applications
- <u>App Note: Low output noise filtering for DC/DC power modules</u>
- Training Video: Understanding, Measuring, and Reducing Output Noise in DC/DC Switching Regulators (part 1)
- <u>Training Video: Understanding, Measuring, and Reducing Output Noise in DC/DC Switching</u> <u>Regulators (part 2)</u>



## **TI.com resources**

## Inverting applications:

- App Note: Configuring the LMZM33606 36V 6A Power Module for negative output
- App Note: Configuring the TPSM53604 36V 4A Power Module for negative output
- App Note: Configuring the LMZ14203 42V 3A Power Module for negative output
- App Note: Configuring the LMZM33603 36V 3A Power Module for negative output
- Datasheet: Using the LMZ34002 40V 2A Negative Output Module
- Evaluation board: LMZ34002 with -3.3V, -5.0V, -12V, -15V selectable outputs
- App Note: Configuring the LMZM23601 36V 1A Power Module for negative output
- App Note: Configuring the TPSM265R1 65V 100mA Power Module for negative output
- <u>App Note: Working with inverting buck-boost converters</u>
- Training video: how to configure a buck into an inverting regulator
- Reference design: -5V at 1.75A using the LMZ36002
- <u>Tech Article: How to create a programmable output inverting regulator</u>



## **TI.com resources**

## Thermal design:

- App note: Practical thermal design with DC/DC Power Modules
- App note: Thermal performance of SIMPLE SWITCHER® Power Modules
- App note: Thermal design by insight, not hindsight
- Training video: Thermal design concepts
- Training video: Managing heat dissipation with DC/DC switching regulators

## Soldering:

- Soldering considerations for power modules
- Power module MSL ratings and reflow ratings



# Key takeaways

- 1. Do not need to be a power expert to design a power supply
- 2. Modules save board area even for the most experienced power designer
- 3. Modules enable you to have good board layout and low EMI
- 4. Modules optimized for typical output voltages
- 5. Converters are more flexible for performance optimization



# Q&A

- Thank you for listening!
- Buck Module Portfolio
- Highlighted products:
  - <u>TPSM5360x</u> 36V, 2A/3A/4A
  - <u>LMZ36002</u> 60V, 2A
  - <u>LMZM23601</u> 36V, 1A
  - <u>TPS82130</u> 17V, 3A
  - <u>TPSM82822</u> 5.5V, 2A (coming soon!)
  - <u>TPSM82810</u> 6V, 4A (coming soon!)
  - <u>TPSM265R1</u> 65V, 100mA (coming soon!)

## Get to market faster with a DC/DC power module

Streamline the DC/DC power supply design process with an integrated-inductor step-down power module. With power modules, TI will help you get to market faster.

- · Optimal converter selected for the specification
- · Reduced component sourcing and qualification
- · Optimized layout for EMI and thermal performance
- · Full characterization across the operating range



SLYP723



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